

# MA6X121 (MA121)

## Silicon epitaxial planar type

For switching circuit

### ■ Features

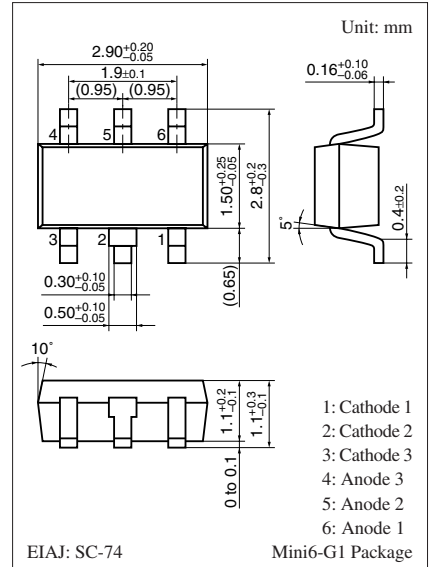
- Three isolated elements contained in one package, allowing high-density mounting
- Short reverse recovery time  $t_{rr}$
- Small terminal capacitance  $C_t$

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	80	V
Maximum peak reverse voltage	$V_{RM}$	80	V
Forward current *1	$I_F$	100	mA
Peak forward current *1	$I_{FM}$	225	mA
Non-repetitive peak forward surge current *1,2	$I_{FSM}$	500	mA
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{sig}$	-55 to +150	$^\circ\text{C}$

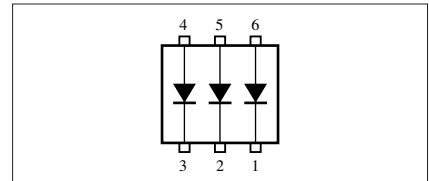
Note) \*1: Value for single diode

\*2:  $t = 1 \text{ s}$



Marking Symbol: M2D

Internal Connection



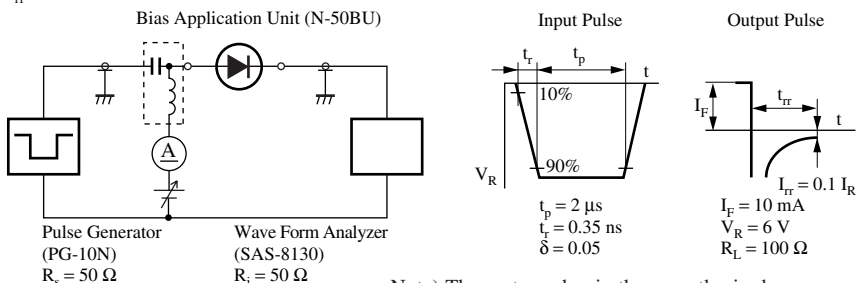
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage	$V_R$	$I_R = 100 \mu\text{A}$	80			V
Reverse current	$I_R$	$V_R = 75 \text{ V}$			100	nA
Terminal capacitance	$C_t$	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			2	pF
Reverse recovery time *	$t_{rr}$	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$ $I_{rr} = 0.1 I_R, R_L = 100 \Omega$			3	ns

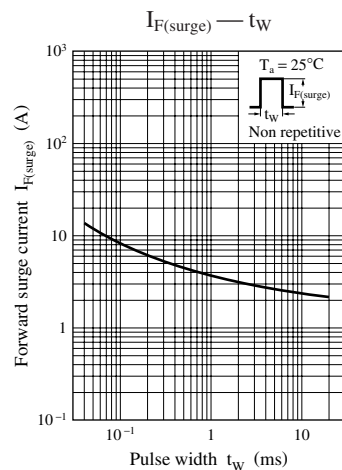
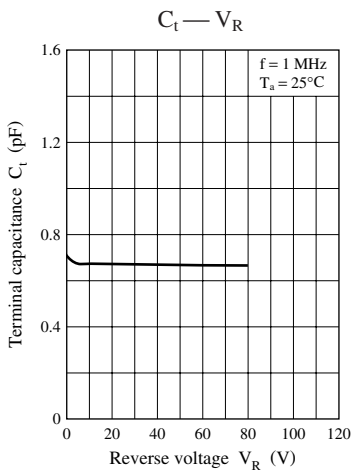
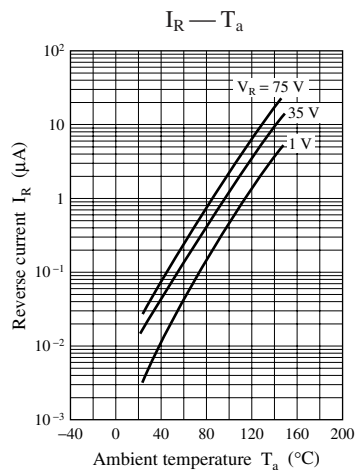
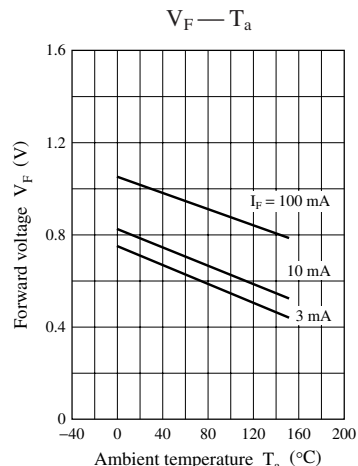
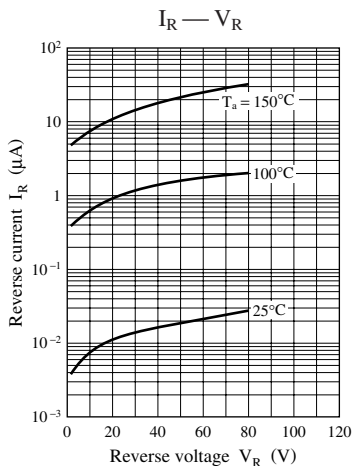
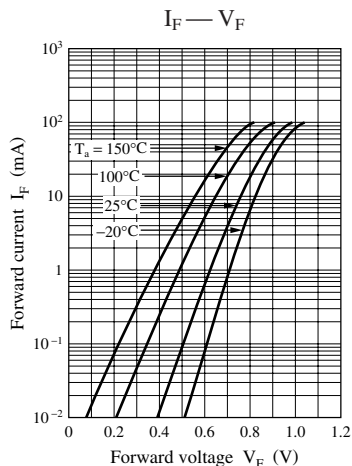
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

3. \*:  $t_{rr}$  measurement circuit



Note) The part number in the parenthesis shows conventional part number.



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